

# Chemical and surface analysis at TE-VSC-SCC

Marcel Himmerlich on behalf of the TE-VSC-SCC team

# Chemical Analyses – Quality Control and R&D

The Chemical Analysis team provides service material analyses and contributes to CERN R&D and scientific studies.

We operate standard characterization systems for gaseous, liquid and condensed matter and develop routines for detection and quantitative analysis.



Benoit Teissandier



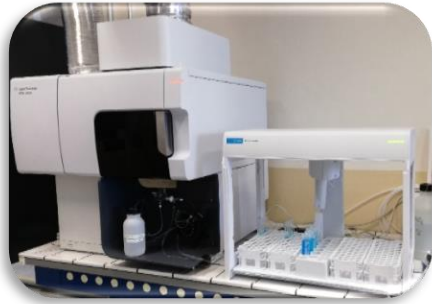
Colette Charvet



Daria Ternova

# Analysis techniques at TE-VSC-SCC Chemistry lab I

## Optical Emission Spectroscopy



*e.g.: Lead detection in CERN buildings*

## Atomic Absorption Spectroscopy



*e.g.: Superconducting cable composition*

## Potentiometric titration



*e.g.: Quality control of surface treatments bath*

## UV-Visible spectroscopy



*e.g.: Water analysis from STEP*

**Quality control of water, surface treatment baths, analysis of metal ions after STEP treatments**

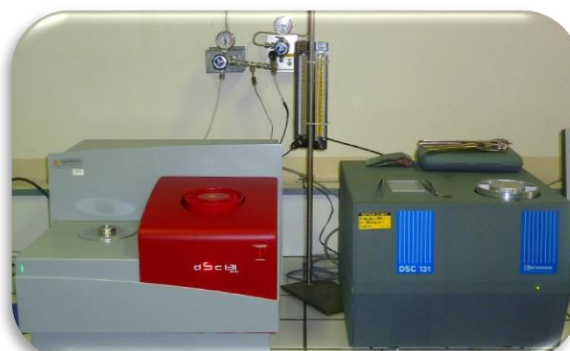
# Analysis techniques at TE-VSC-SCC Chemistry lab II

## FTIR spectroscopy



*e.g.: Evaluation of surface cleanliness for **UHV** applications, Polymer identification*

## Differential Scanning Calorimetry



*e.g.: Polymer **Tg** Measurement*

## Thermogravimetry



*e.g.: Mineral filler quantification in polymers*

# Analysis techniques at TE-VSC-SCC Chemistry lab III

## X-ray fluorescence spectroscopy



*e.g.: Elemental composition of metallic parts, In-situ thickness measurement of coatings*

## Karl Fischer Coulometry

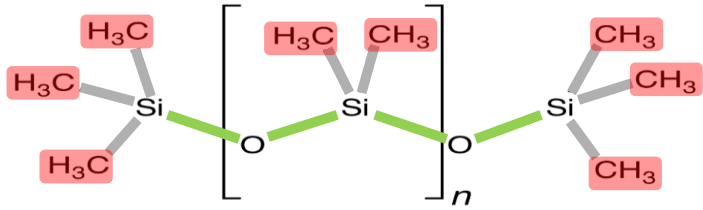


*e.g.: Quality control of the LHC experiments gas and/or cooling fluid*

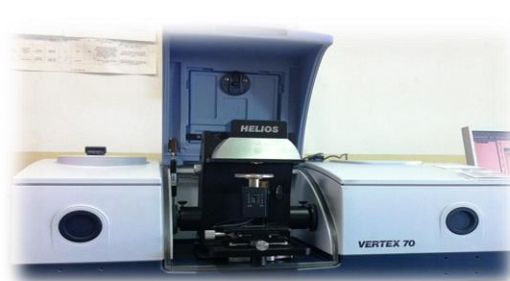
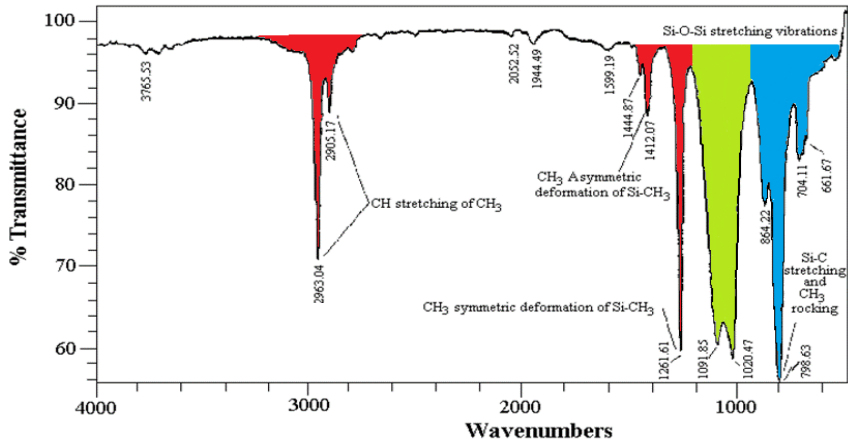
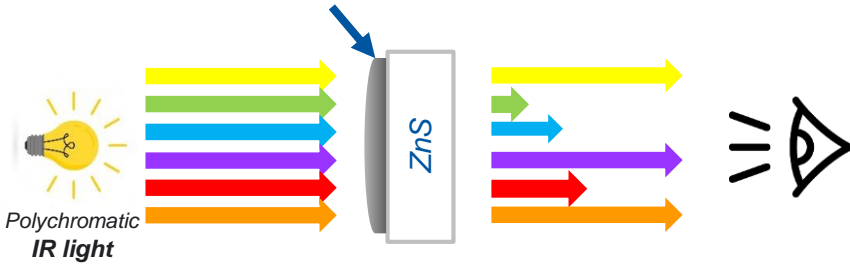
## Gas Chromatography



# Analysis of organic compounds by IR spectroscopy



e.g.: Silicone oil



Lab. Spectrometer : Bruker Vertex 70



Handheld : Agilent Exoscan 4100

## Characterization of solids, liquids & gases

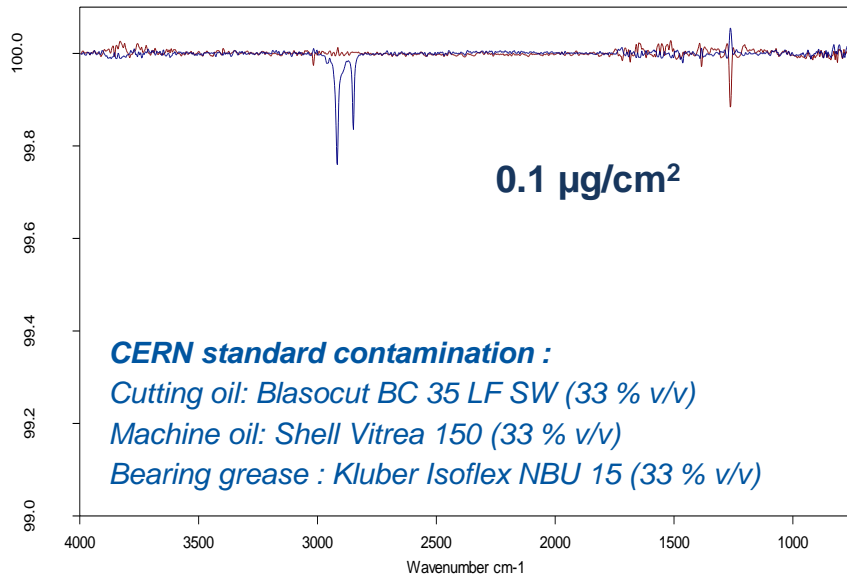
- “Silicon free” - Quality control of pipes used to build gas detectors
- Cooling fluids (and gas) identification and quantification of contaminants
- Identification of Polymers

## Quantification to ppm level (after calibration)

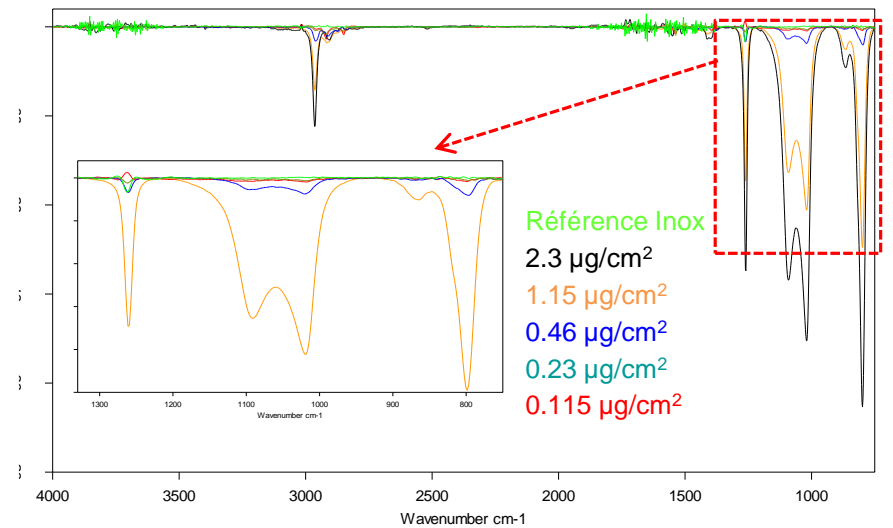
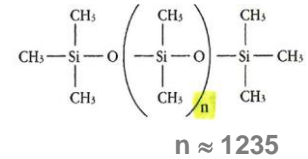
- Cleanliness assessment for gas system detector or UHV applications
- Cooling fluids purity

# Quantification and detection limit by IR spectroscopy

## Detection limit of hydrocarbon contamination on stainless steel surface



## Detection limit of Dimethylsiloxane on stainless steel surface



**Detection limit ≈ 1 molecular layer**

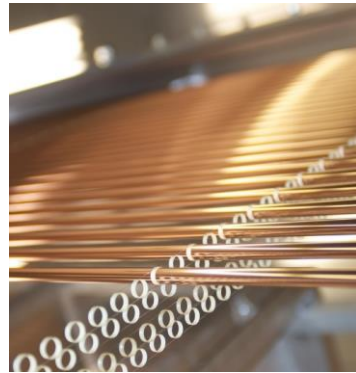
Report : EDMS 1332721 (B. Teissandier)

# Hostaphan<sup>®</sup> (PET) foils with Cu/Au coatings (NA62 - Straws Tracker)

## Thickness measurement of Au & Cu coatings

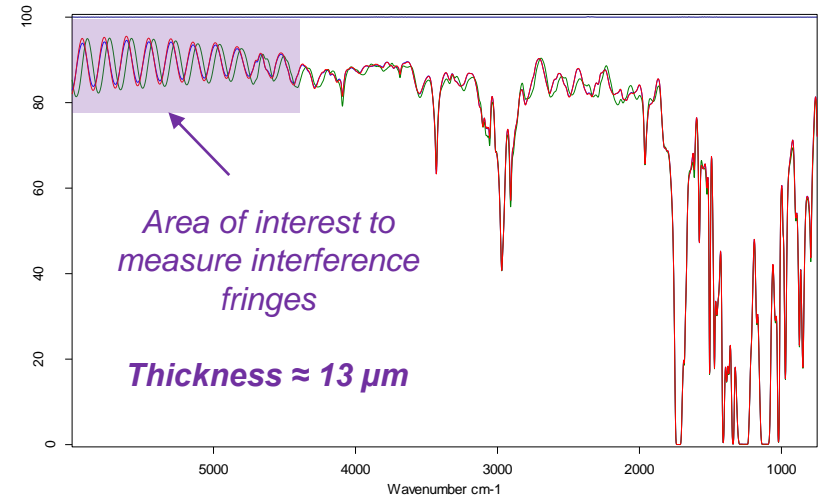
1. Chemical dissolution of metallic coatings with aqua regia (on defined area)

2. Quantification of Au and Cu by ICP-OES spectroscopy



## Thickness measurement of Hostaphan foil

1. Chemical dissolution of metallic coatings with aqua regia
2. Infrared spectroscopy analysis in transmission mode

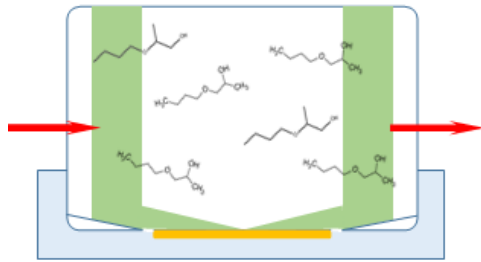


Analysis report : EDMS [2747287](#) & [2823835](#) (B. Teissandier)

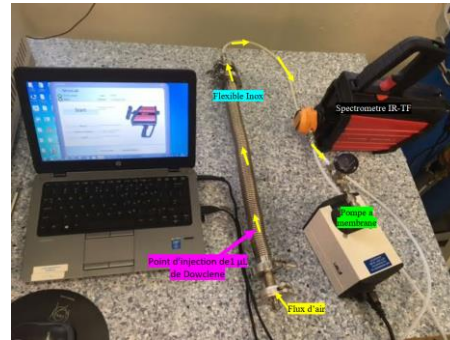


# Search for residual cleaning solvent (Dowclene 1601) in CMS Resistive Plate Chamber (RPC) gas system

## Lab-based validation



Principle of FTIR gas cell

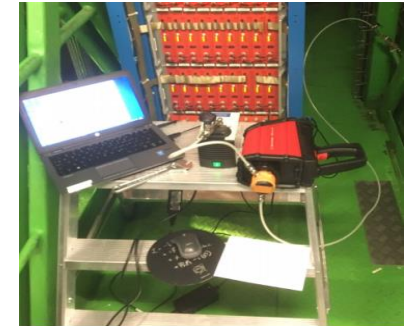


Dowclene detection by FTIR

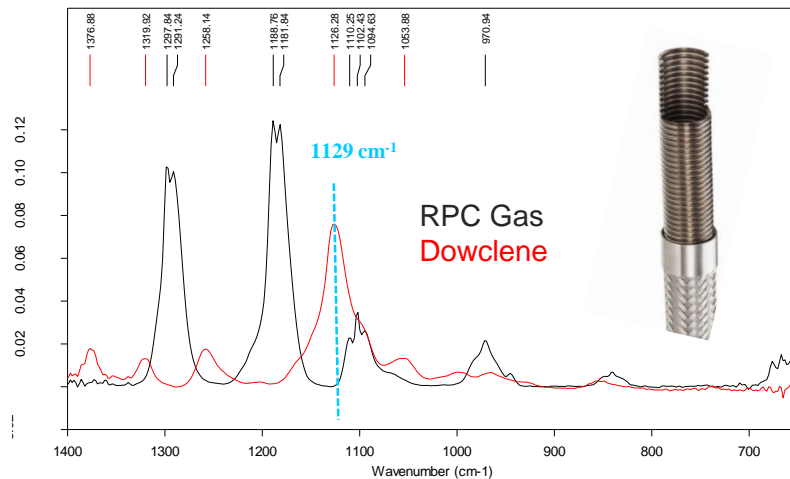
## Measurements in CMS RPC gas system



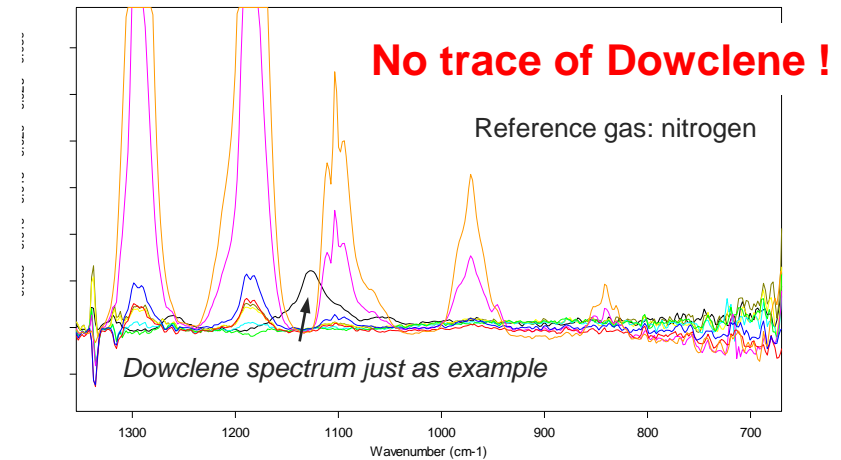
Sampling in CMS



FTIR on CMS RPC gas system



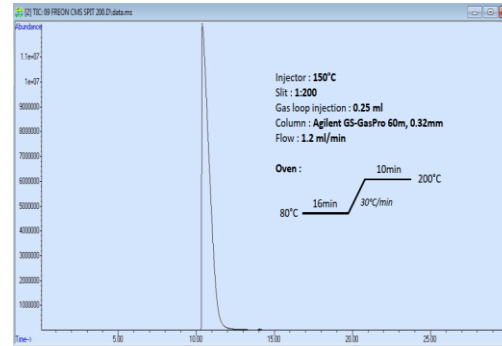
RPC gas:  $\text{CH}_2\text{FCF}_3$  /  $\text{SF}_6$  /  $\text{C}_4\text{H}_{10}$



Analysis report : EDMS [2716850](#) (B. Teissandier)

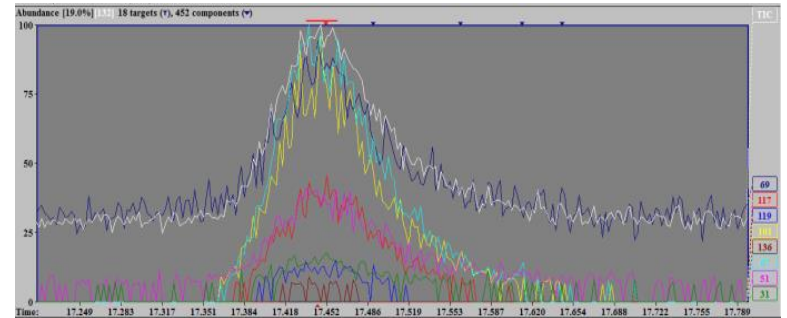
# R134a GC/MSD Analysis (CMS RPC)

## Instrumentation & method

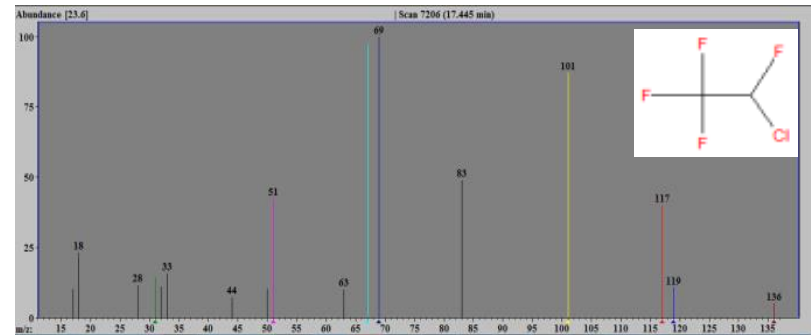
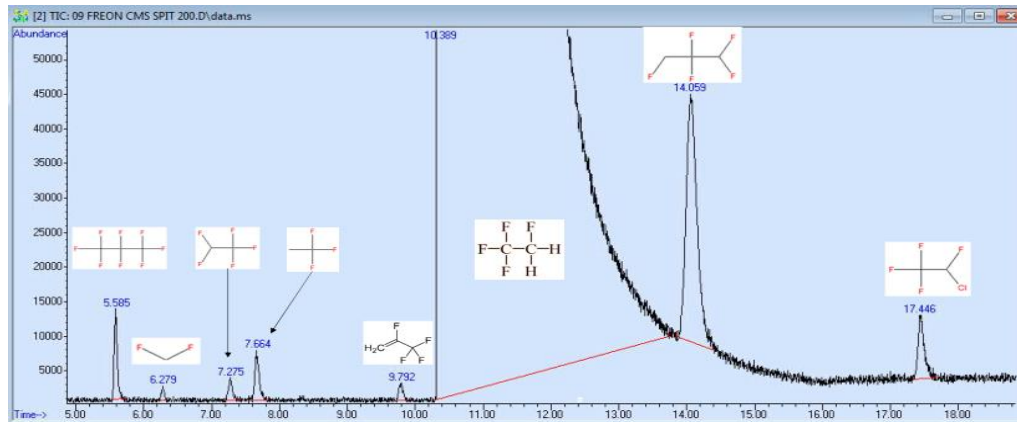


## Example of gas traces identification

@ 17.4 min, identification of  $C_2HClF_4$



## Impurities in $CH_2FCF_3$



Colors indicate signals from  $C_2HClF_4$

R134a =  $CH_2FCF_3$  (tetrafluorethane)

$C_2HClF_4$  (Chloro-tetrafluorethane)

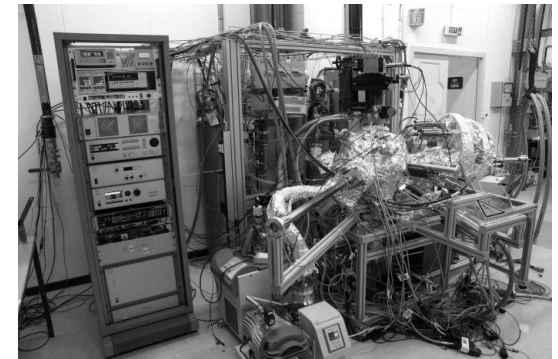
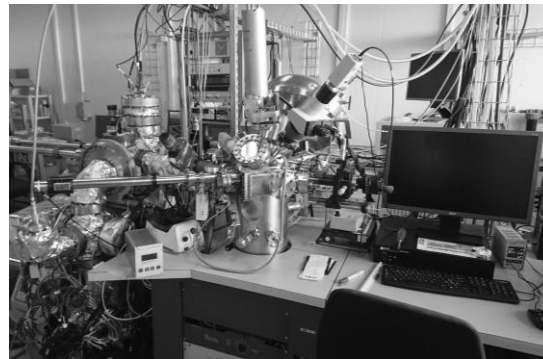
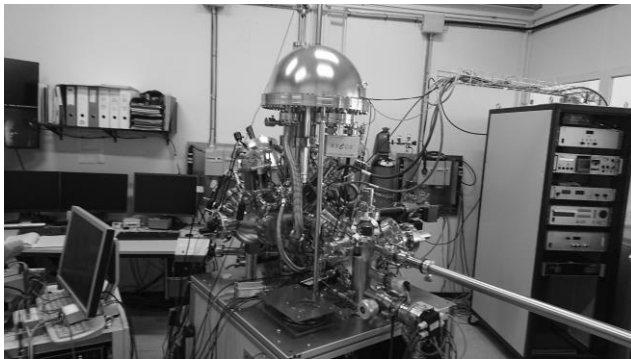
# Surface Analyses – Quality Control and R&D

The Surface Analysis team provides service material analyses and contributes to CERN R&D and scientific studies.

We operate UHV systems for surface spectroscopy and thin film characterization on small test samples.

## *Main methods:*

- Secondary Electron Yield (SEY) measurements
- X-ray Photoelectron Spectroscopy (XPS)



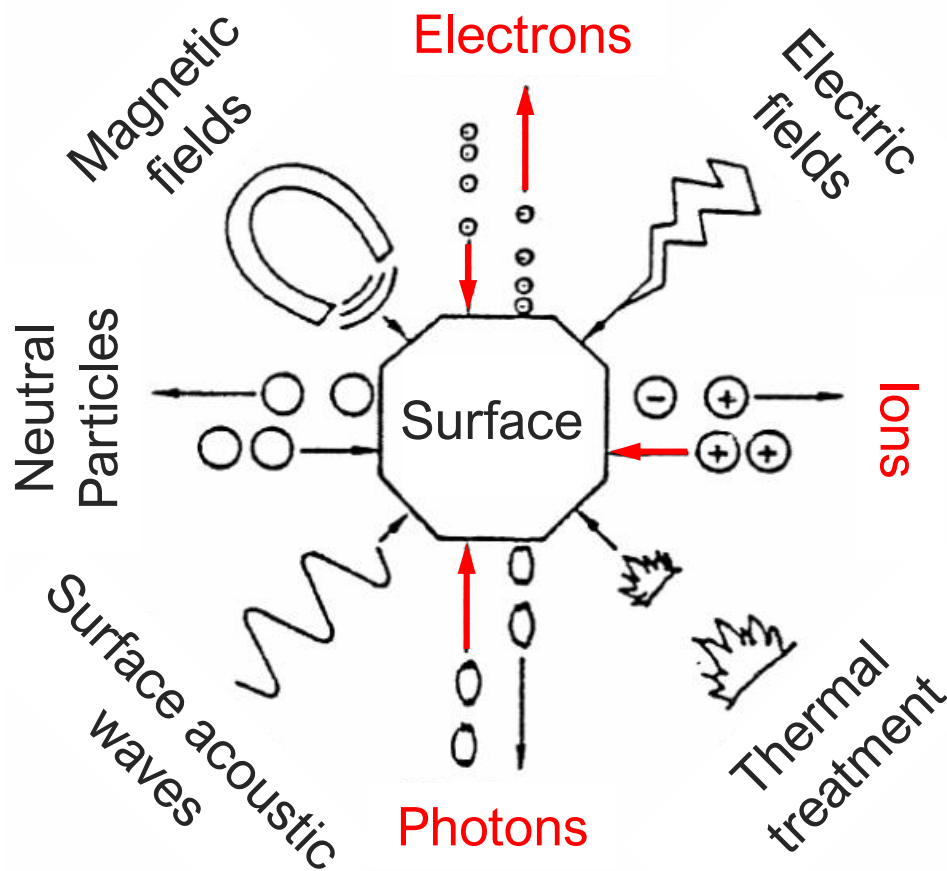
# Surface Analyses – Quality Control and R&D

- We provide surface and thin film analysis expertise for the CERN community and projects.
- If a surface or thin film analysis technique does not exist at CERN → we advise and mediate tests at external partners and institutes

**Examples:** Secondary Ion Mass Spectroscopy profiling & Ion Scattering Spectroscopy for Hydrogen content in thin metal films

Laterally resolved Auger Electron Spectroscopy depth profiling for surface composition analysis of superconducting cables

# The «playground» of surface analysis



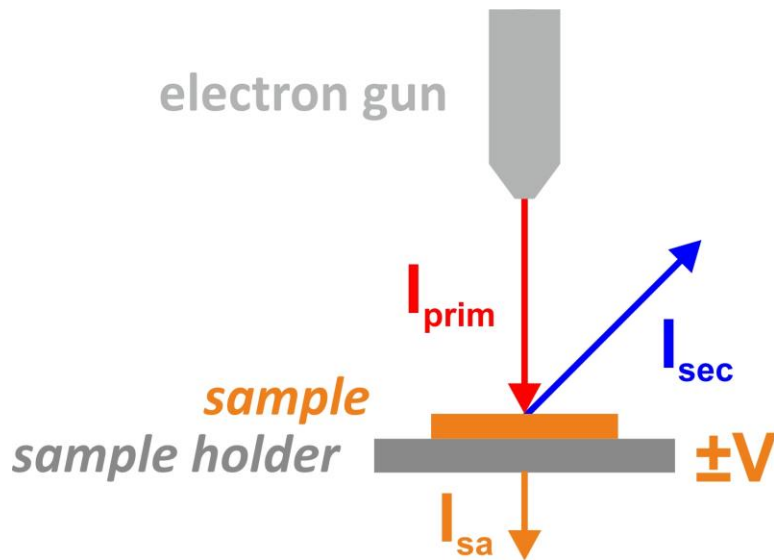
Laterally resolved analysis  
→ Microscopy

Spectrally resolved analysis  
→ Spectroscopy

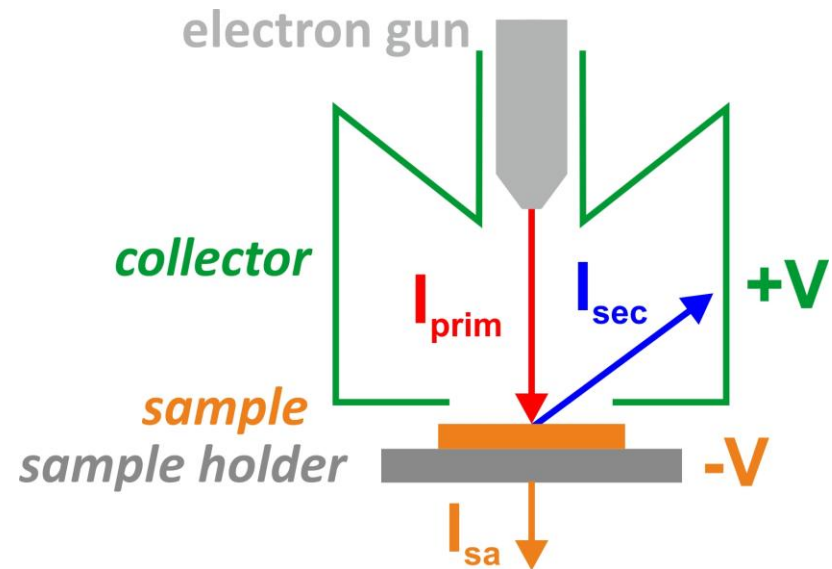
Combination of lateral magnification and spectral selection  
→ Spectromicroscopy  
→ Microspectroscopy

adapted from M. Henzler and W. Göpel, Oberflächenphysik des Festkörpers

# Angle-integrated Secondary Electron Yield

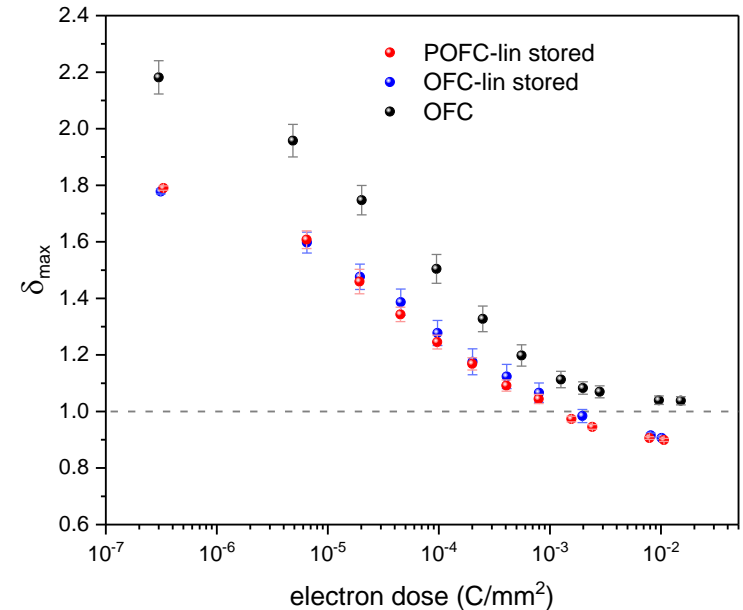
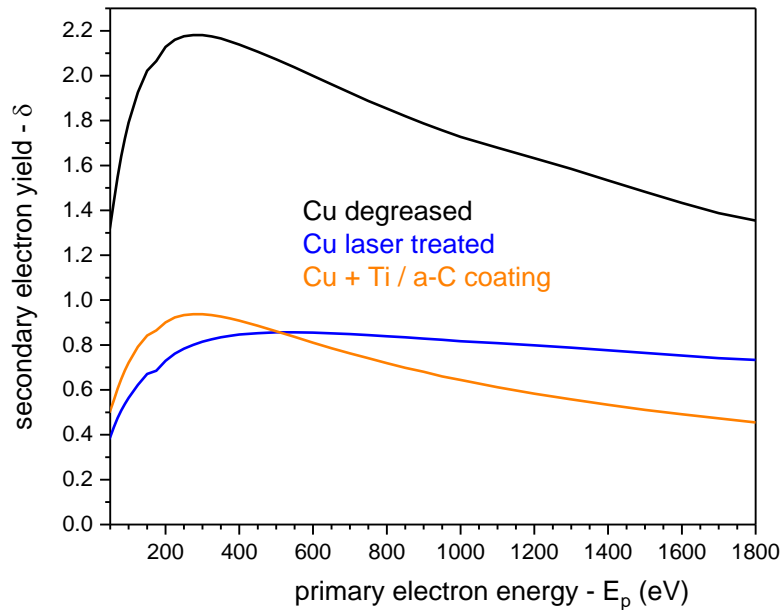
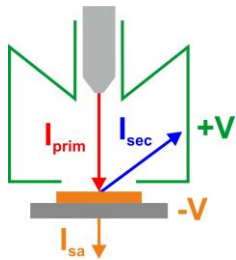


$$\delta(E) = \frac{I_{sec}(E)}{I_{prim}(E)} = \frac{I_{+V} - I_{-V}}{I_{+V}}$$



$$\delta(E) = \frac{I_{sec}(E)}{I_{prim}(E)} = \frac{I_{col}}{I_{col} + I_{sa}}$$

# Secondary Electron Yield & Conditioning

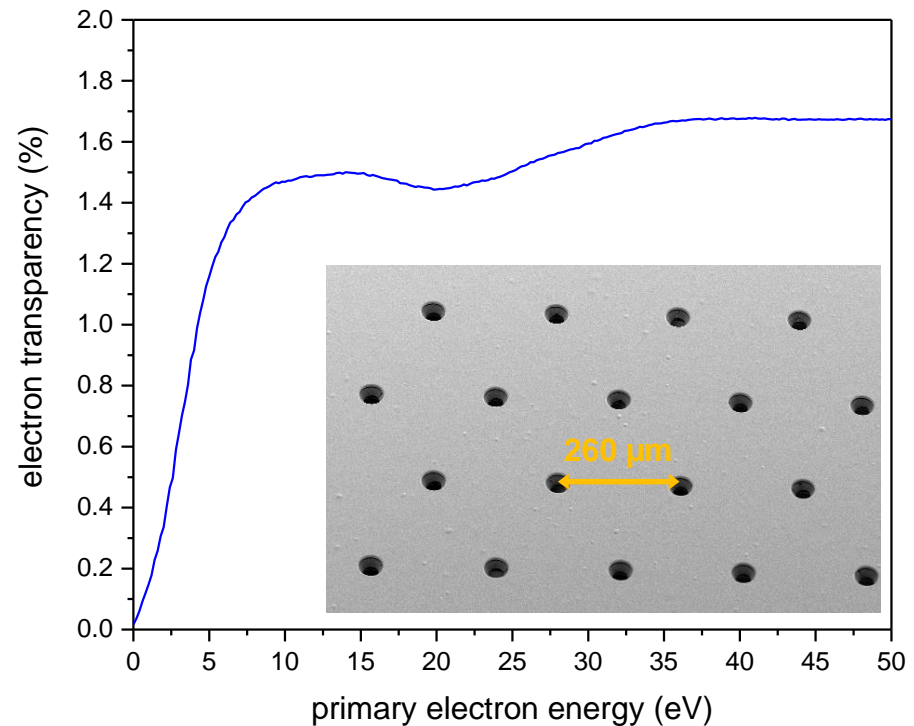
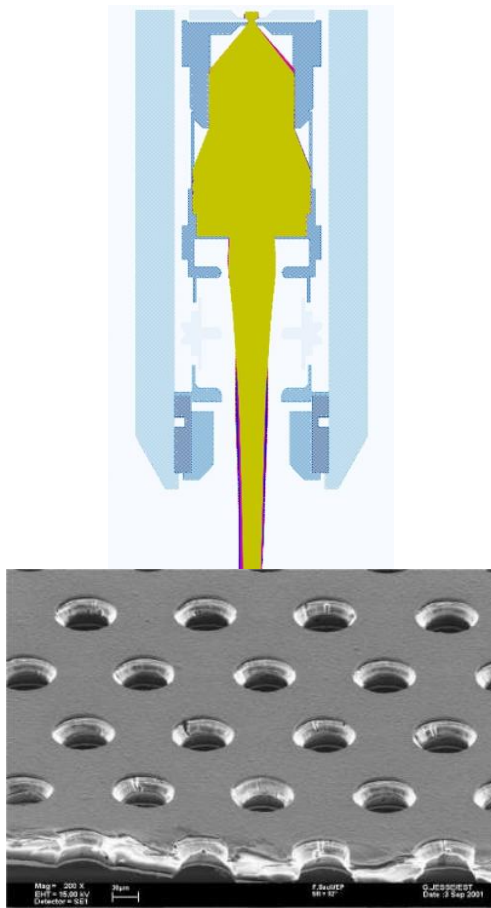


## Other options:

- Electron induced surface modification (conditioning)
- Work function measurements
- Incidence angle dependent SEY analyses
- SEY measurements of insulating samples

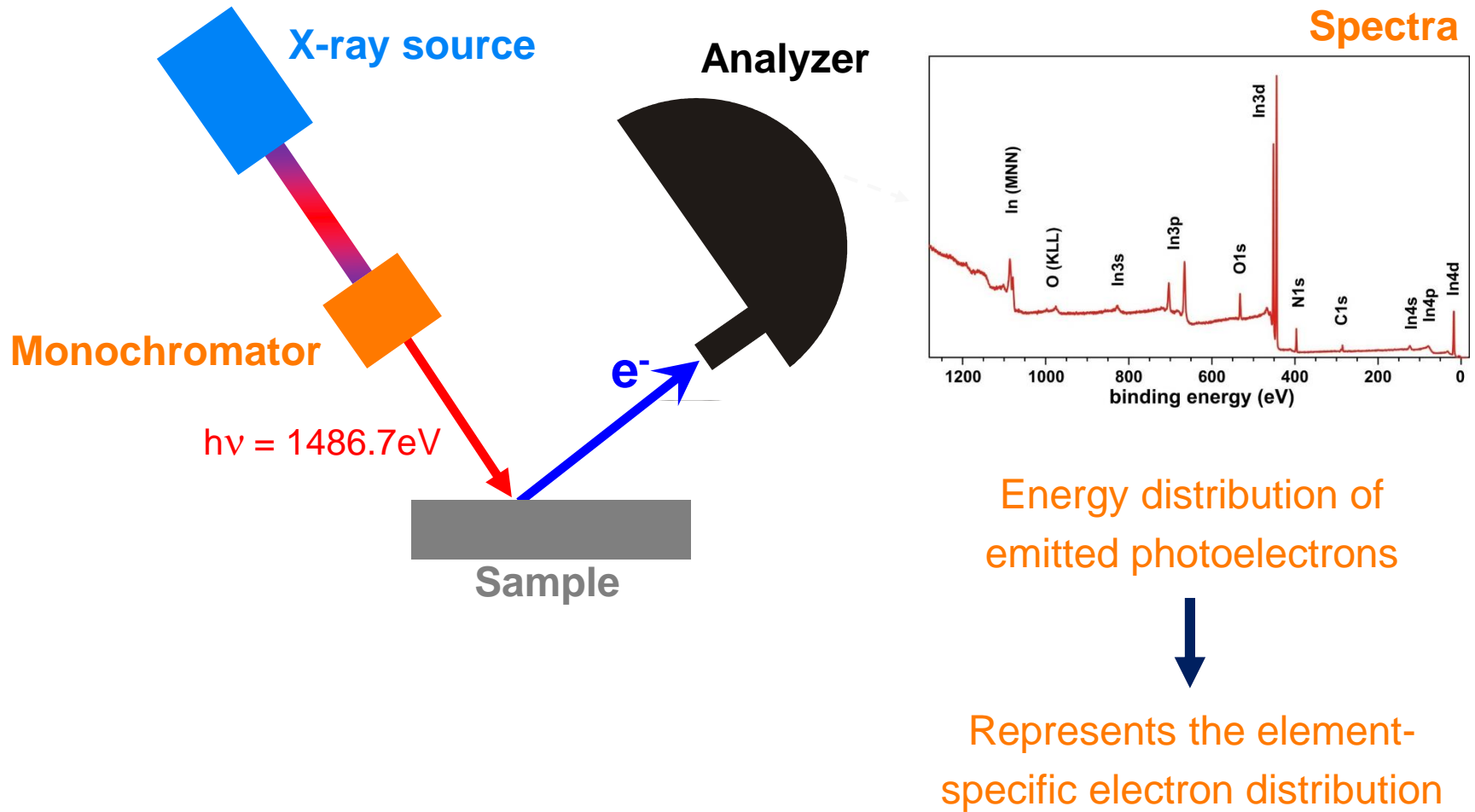
# Electron transmission through GEM foils and graphene layers

Adaption of UHV setup with versatile electron source for transmission (current) measurement





# X-ray Photoelectron Spectroscopy



# Results from Photoelectron Spectroscopy

## ***Surface chemical composition***

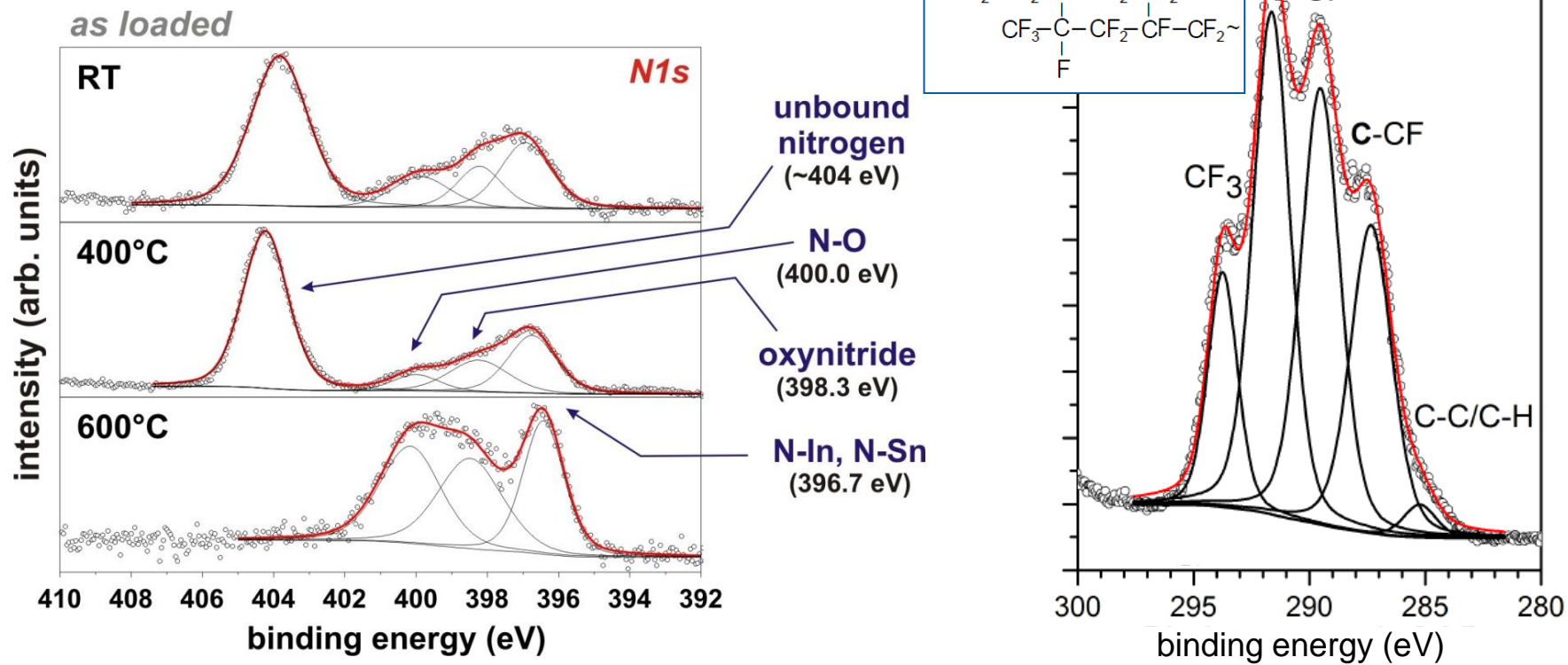
- Surface and film stoichiometry (elemental composition)
- Adsorbates, contamination & surface functionalization
- Chemical modification of surfaces
- Degradation & passivation

## ***Surface electronic properties (in-situ studies)***

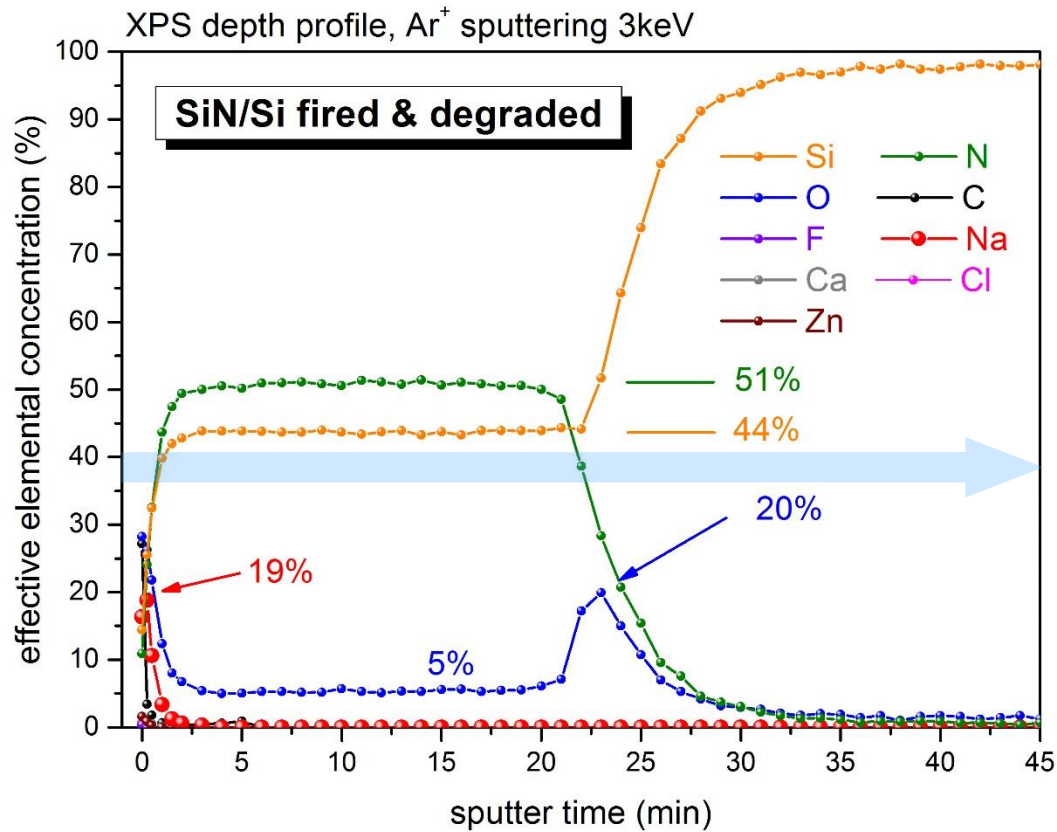
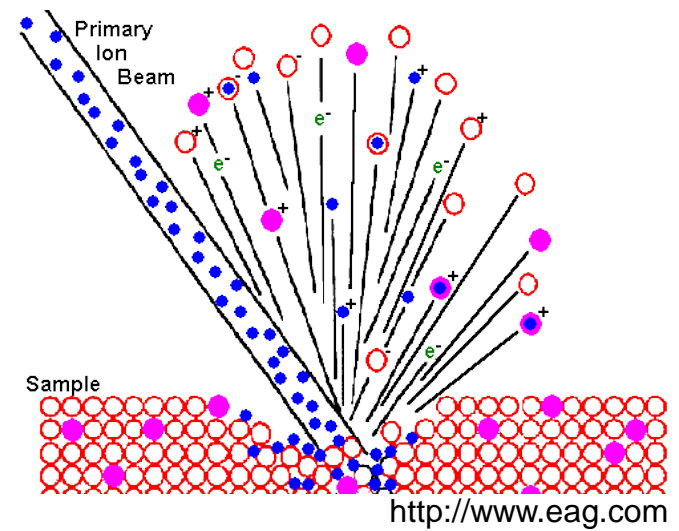
- Valence band density of states
- Work function, surface band bending, surface dipoles
- Band offsets at interfaces
- Charge transfer processes

# Analysis of chemical states

Electron binding energy depends on the actual chemical bond configuration of the material and the nature & electronegativity of the neighboring atoms

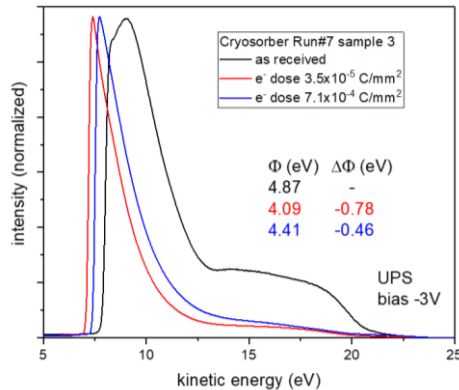


# Sputter depth profiling

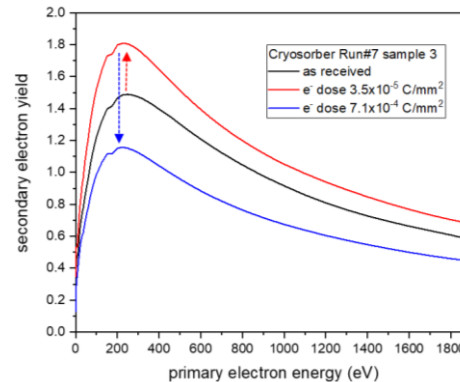


# UV or e<sup>-</sup> induced electron spectroscopy

- UV source to measure work function and valence band



$\Phi \leftrightarrow \delta$

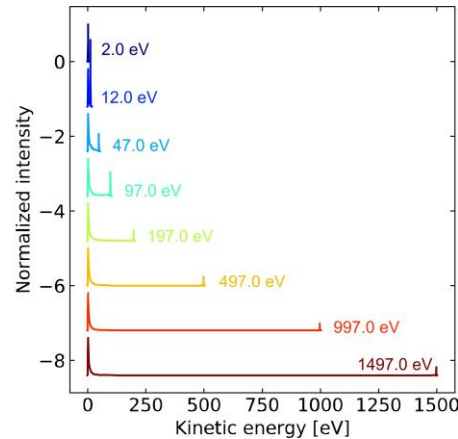
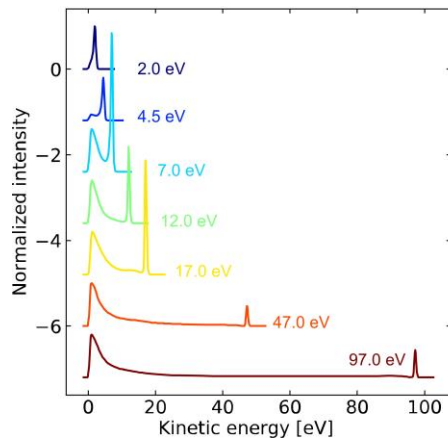


$E_{\text{photon}}$

21.2 eV  
&  
40.8 eV



- Electron source to measure angular-resolved SE spectroscopy



$E_{\text{electron}}$

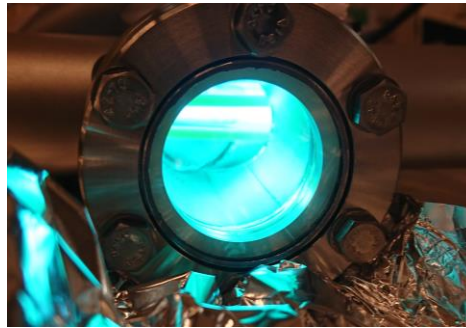
1 eV  
-  
1500 eV

# Sample preparation & surface modification

- Characterization of surface property changes during treatments in vacuum and/or reactive atmosphere ( $p \approx 10^{-2}$  mbar)



Heating up to 800°C



UV-C irradiation



Plasma exposure

+ injection of gaseous species

Characterization of:

- Chemical reduction/oxidation and functionalization processes
- Physical cleaning/etching of surfaces

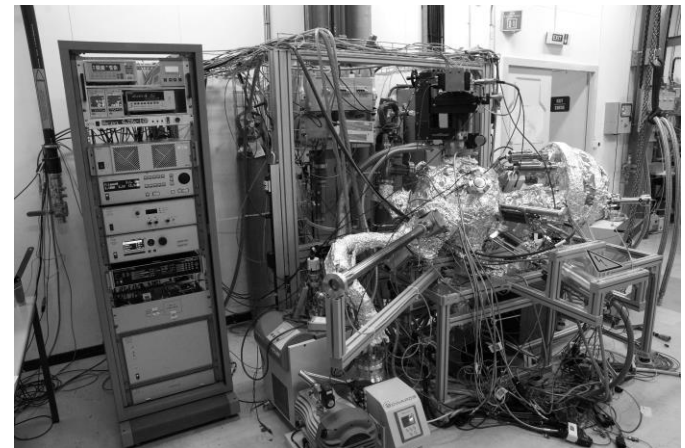
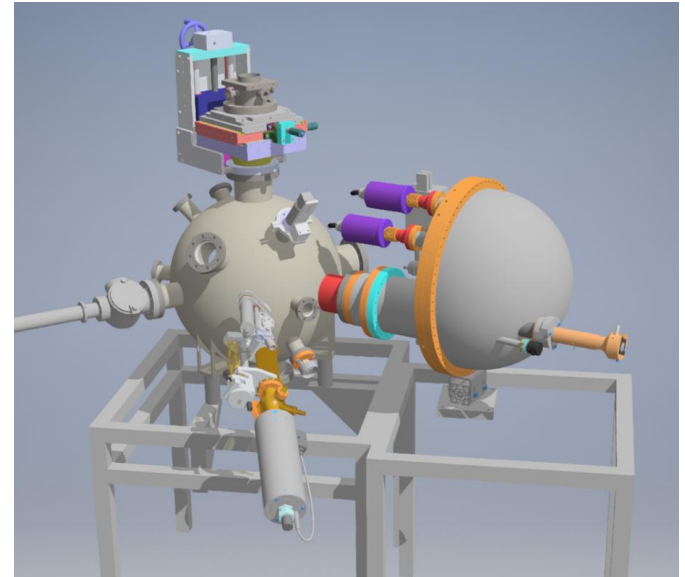
# Surface analyses at cryogenic temperatures



Thermal shield

Sample

- Cryogenic cooling of samples to 15 K
- SEY, SES, conditioning and XPS analyses at variable temperature
- Optional injection of gases to characterize surface reactions

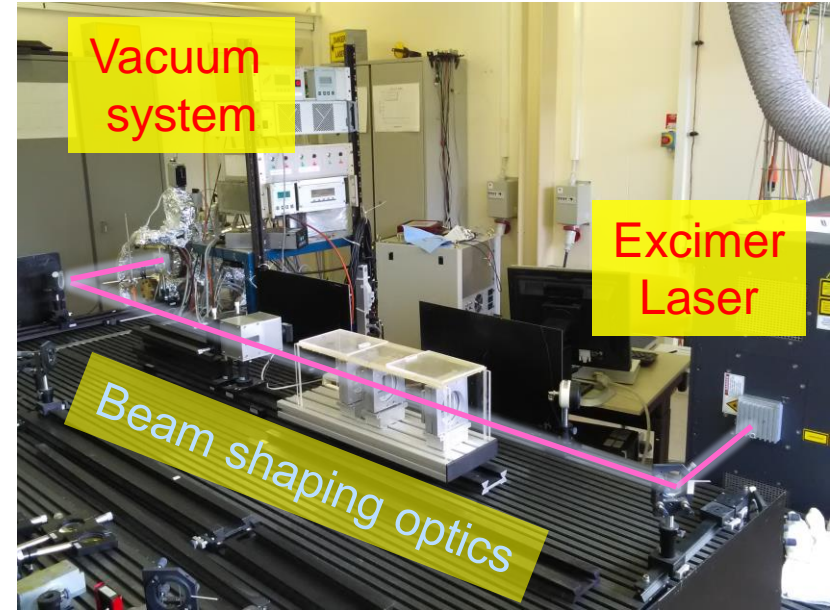


# Pulsed laser ablation

- Ablation of thin films on metallic substrates in UHV by 248 UV laser
- Accumulation of the trapped noble gas in the ablation chamber
- Evacuation of the ablation volume via analysis chamber with a calibrated RGA allows to determine the gas quantity ( $p \cdot V \rightarrow$  number of gas atoms)
- Film thickness  $\times$  ablated area ( $2 \text{ mm}^2$ )  $\rightarrow$  compute number of ablated atoms
- **Gas content** =  $\frac{\# \text{ noble gas atoms}}{\# \text{ ablated atoms}}$

## Options:

- laser-fatigue tests
- pulsed laser deposition from target



## Key parameters:

- Possibility to measure all noble gases trapped in thin films up to  $5 \mu\text{m}$  thickness
- Gas content as low as 10 ppm detectable

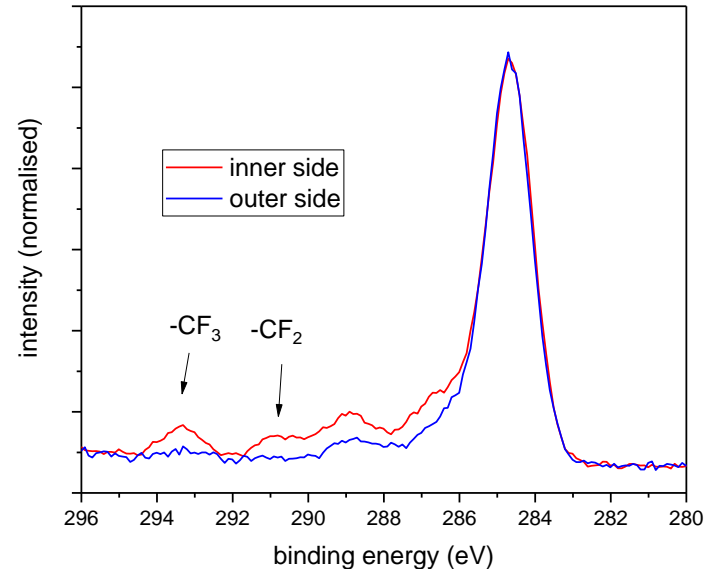
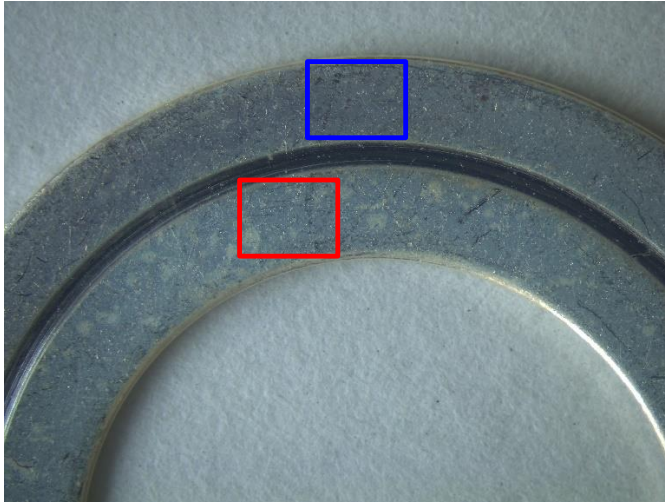


# Typical surface analysis tasks

- Contamination analysis after cleaning or material processing
- Thin film composition characterization
- Identification of chemical bonds and adsorbates at surfaces
- SEY qualification of materials and surface processing including electron-induced conditioning tests
- In-situ modification of surfaces & model experiments to develop surface technologies
- Development of new routines for material characterization

# XPS: example I

## Impurities of Ag-coated gaskets from LHCb SciFi baby demo plant

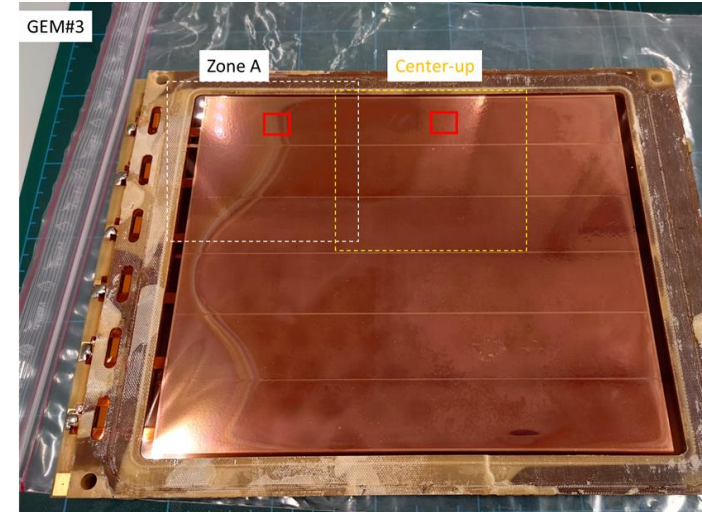
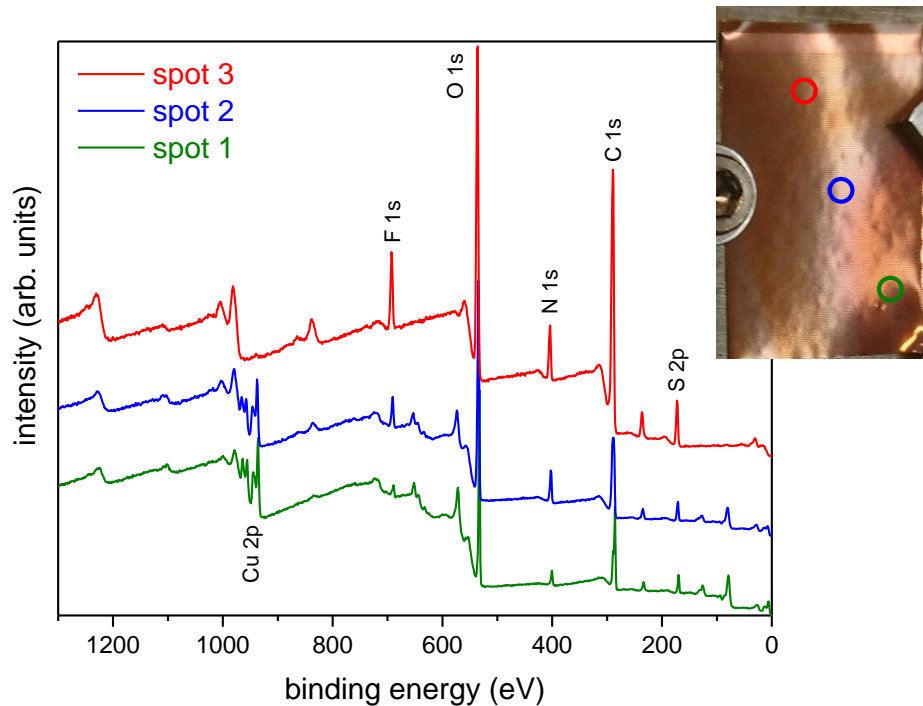


- Circuit operated with NOVEC 649 including *Dodecafluoro-2-methylpentan-3-one* (CF<sub>3</sub>CF<sub>2</sub>C(O)CF(CF<sub>3</sub>)<sub>2</sub>)  
→ XPS spectra indicate absence of corrosion reactions but only stains from dried operation liquid

see EDMS [2780062](#)

# XPS: example II

Analysis of triple-GEM detector after operation in LHCb with CF<sub>4</sub>-based gas mixture (40% CF<sub>4</sub>, 15% CO<sub>2</sub>, 45% Ar)



N, S and C signals indicate polymeric contamination film  
→ Same residuals found on glued frame (see also EDMS [2802473](#) - SEM/EDX by A.T. Fontenla)

# Thanks for your attention.



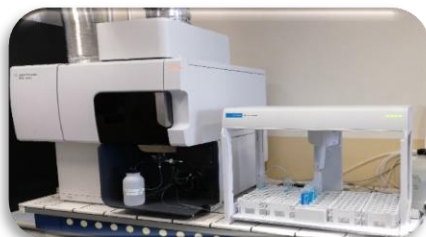
# Analysis techniques at TE-VSC-SCC Chemistry lab

## FTIR spectroscopy



*e.g.: Evaluation of surface cleanliness for UHV applications, Polymer identification*

## Optical Emission Spectroscopy



*e.g.: Lead detection in CERN buildings*

## Atomic Absorption Spectroscopy



*e.g.: Superconducting cable composition*

## Differential Scanning Calorimetry



*e.g.: Polymer T<sub>g</sub> Measurement*

## X-ray spectroscopy



*e.g.: Composition of metallic parts, In-situ Thickness of coatings*

## Karl Fischer Coulometry



*e.g.: Quality control of the LHC experiments cooling fluid*

## Gas Chromatography



## Thermogravimetry



*e.g.: Mineral filler quantification in polymers*

## Potentiometric titration



*e.g.: Quality control of surface treatments bath*

## UV-Visible spectroscopy



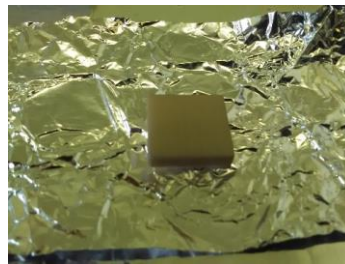
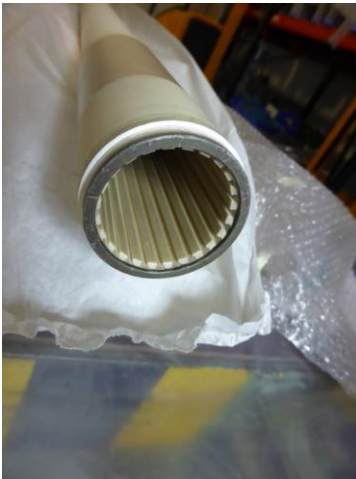
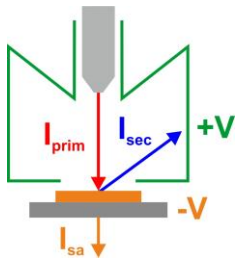
*e.g.: Water analysis from STEP*

# Pulsed SEY for Insulators

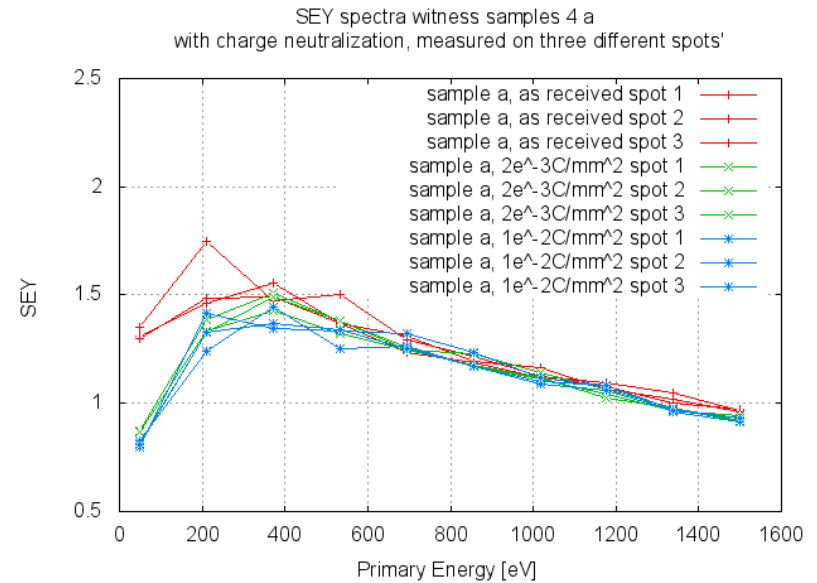
**Problem:** - Difficulties to measure continuous-current SEY on insulators due to surface charging

**Solution:** - Exposure to 30  $\mu\text{s}$  long electron pulses ( $2 \times 10^{-12}$  C per data point) on a spot of about 10  $\text{mm}^2$  to minimize charging

- Time-resolved measurement of primary and secondary electron current
- Neutralization with low energy electrons after each pulse to compensate positive charges



Coated Ceramic chamber for LHC injection kicker magnets and witness sample (Photos courtesy M. Barnes SEY\_861)



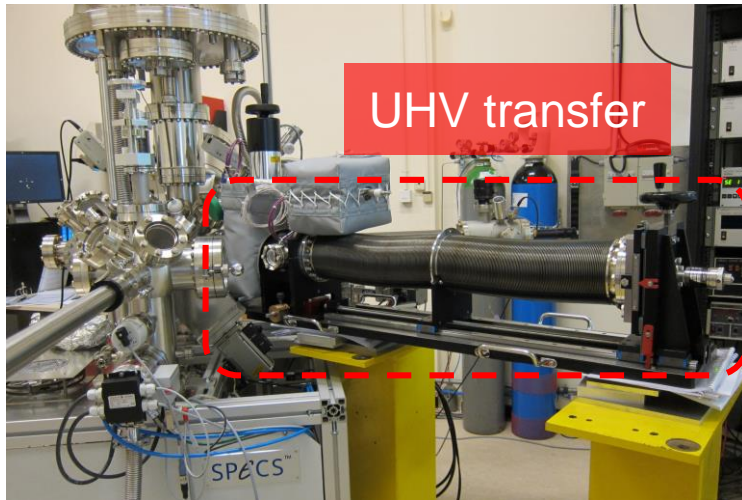
SEY spectra on witness sample with two conditioning steps

# XPS: Practical and technical aspects

- Depth of information in XPS: 5-10 nm
- Detection limit 0.01 – 0.1 at.%
- Lateral resolution limited to 200  $\mu\text{m}$
- Depth profiling up to 2  $\mu\text{m}$
- Samples must be vacuum-compatible (low vapor pressure, no pencil marks, no fingerprints, contamination- and oil-free)
- Flat samples preferred & maximum sample thickness ~1 cm
- Minimum sample size 4x4 mm<sup>2</sup>, maximum 45x45 mm<sup>2</sup>
  
- Hydrogen not directly detectable
- Some organic materials are sensitive to X-ray damage
- Insulating samples: limitations in analysis of bond configuration



# Vacuum Transfers for Surface Characterization



Characterization of Photocathodes with SY-STI-LP

- ✓ Vacuum transfer systems for sensitive and reactive samples are essential to avoid surface oxidation and adsorption of ambient species
- ✓ Solutions exist for analysis of photocathodes, samples from the SPS to study beam-surface interaction

Vacuum transfer solutions can be adapted to new needs and geometries.

